**Strategic Wireless Applications**

**Edited by: Zhongmin Yu**

**Last Edited 10/07/17**

**Phone:** 408-601 1000

## PCB Project/Physical Description

Ref. Design Project Number MAX31341 RevC EVKIT

Quantity: 30pcs Turn (working days) : 10days

Layers: 2 PCB Thickness: 0.062” +/-10%. Dielectric: FR-4

RF characteristic impedance: 50ohm—top layer, only traces near Ant (X16) Dielectric Constant: 4.5

Min. drill size(finish): 8mils. All through Vias

Min. line width/spacing: 6 mils / 10 mils

Plating: Immersion Gold over 100mils of nickels Weight: 2-10 Micro-Inches

Board dimensions: 2.3’’x2.3’’ ( see gerber) 120 of surface mount pads

Approx. # of thru holes:550, Silkscreen: White Solder Mask: LPI Green

Scoring (location): N/A Additional features: N/A

# Tolerance

Board Dimensions: +/-0.010”

Plated Thru Holes: +/-0.003”

Pattern to Pattern: +/-0.005”

Solder Mask Pattern: +/-0.005”

Legend to Legend: +/-0.007”